



REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: T151019-4A	Yulin	2016.05.03
B	ECN NO: S161130-C	JIE-FU	2017.02.13

- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
 - CONTACT RESISTANCE: 50mΩ MAX.
 - INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT, IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES.
 - INSERTION FORCE: 0.3 - 3.0Kg.
 - WITHDRAWAL FORCE: 0.3 - 3.0Kg.
 - AFTER TEST, CONTACT RESISTANCE: 120mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - MARKING: MARK "YMMDD" ON BOTTOM OF CONNECTOR.
 - PACKING: TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:

I	SHELL	1	COPPER ALLOY, 0.2t	Ni 60u"Min.
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA; GOLD FLASH ON SOLDER AREA; ALL OVER 50u" Ni.
F	TRANSFER TERMINAL	1	COPPER ALLOY, 0.2t	
E	TIP SPRING	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA; Matte Sn 120u" ON SOLDER AREA; ALL OVER 50u" Ni.
D	RING A	1	COPPER ALLOY, 0.2t	
C	RING B	1	COPPER ALLOY, 0.2t	
B	EARTH	1	COPPER ALLOY, 0.2t	
A	BODY	1	PA4T+30%GF(TX1) UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES			Singatron Enterprise Co., Ltd. 信音企業股份有限公司	
DECIMALS:		ANGLES:	TITLE	
X	:±0.5	X	:±2'	3.5Ø PHONE JACK PART NO. 2SJ3095-099111F SCALE 4:1 UNIT: mm SIZE: A3 SHEET: 1 OF 1 REV: B CUSTOMER COPY
X.X	:±0.3	X.X	:±1'	
X.XX	:±0.2			